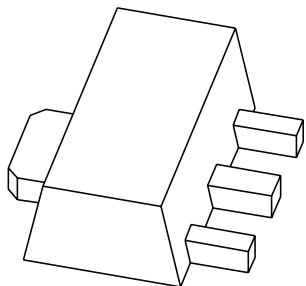


DATA SHEET



BSR40; BSR41; BSR42; BSR43 NPN medium power transistors

Product data sheet
Supersedes data of 1999 Apr 28

2004 Dec 13

NPN medium power transistors**BSR40; BSR41;
BSR42; BSR43****FEATURES**

- High current (max. 1 A)
- Low voltage (max. 80 V).

APPLICATIONS

- Thick and thin-film circuits
- Telephony and general industrial applications.

DESCRIPTION

NPN medium power transistor in a SOT89 plastic package. PNP complements: BSR30; BSR31 and BSR33.

MARKING

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
BSR40	AR1	BSR42	AR3
BSR41	AR2	BSR43	AR4

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

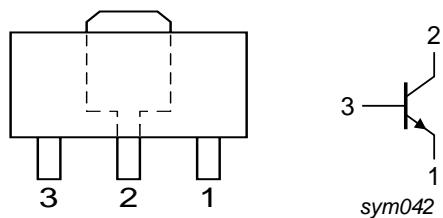


Fig.1 Simplified outline (SOT89) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BSR40	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89
BSR41			
BSR42			
BSR43			

NPN medium power transistors

BSR40; BSR41; BSR42;
BSR43**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage BSR40; BSR41 BSR42; BSR43	open emitter	– –	70 90	V V
V_{CEO}	collector-emitter voltage BSR40; BSR41 BSR42; BSR43	open base	– –	60 80	V V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	1	A
I_{CM}	peak collector current		–	2	A
I_{BM}	peak base current		–	0.2	A
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	–	1.35	W
T_{stg}	storage temperature		–65	+150	$^\circ\text{C}$
T_j	junction temperature		–	150	$^\circ\text{C}$
T_{amb}	ambient temperature		–65	+150	$^\circ\text{C}$

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm².
For other mounting conditions, see "Thermal considerations for SOT89 in the General Part of associated Handbook".

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	93	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point		13	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm².
For other mounting conditions, see "Thermal considerations for SOT89 in the General Part of associated Handbook".

NPN medium power transistors

BSR40; BSR41; BSR42;
BSR43**CHARACTERISTICS** $T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$I_E = 0 \text{ A}; V_{CB} = 60 \text{ V}$	–	100	nA
		$I_E = 0 \text{ A}; V_{CB} = 60 \text{ V}; T_j = 150^\circ\text{C}$	–	50	μA
I_{EBO}	emitter-base cut-off current	$I_C = 0 \text{ A}; V_{EB} = 5 \text{ V}$	–	100	nA
h_{FE}	DC current gain BSR40; BSR42 BSR41; BSR43	$I_C = 100 \mu\text{A}; V_{CE} = 5 \text{ V}; \text{note 1}$	10	–	
		30	–		
	$I_C = 100 \text{ mA}; V_{CE} = 5 \text{ V}; \text{note 1}$	40	120		
			100	300	
	DC current gain BSR40; BSR42 BSR41; BSR43	$I_C = 500 \text{ mA}; V_{CE} = 5 \text{ V}; \text{note 1}$	30	–	
		50	–		
V_{CEsat}	collector-emitter saturation voltage	$I_C = 150 \text{ mA}; I_B = 15 \text{ mA}; \text{note 1}$	–	250	mV
		$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}; \text{note 1}$	–	500	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 150 \text{ mA}; I_B = 15 \text{ mA}; \text{note 1}$	–	1	V
		$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}; \text{note 1}$	–	1.2	V
C_c	collector capacitance	$I_E = i_e = 0 \text{ A}; V_{CB} = 10 \text{ V}; f = 1 \text{ MHz}$	–	12	pF
C_e	emitter capacitance	$I_C = i_c = 0 \text{ A}; V_{EB} = 0.5 \text{ V}; f = 1 \text{ MHz}$	–	90	pF
f_T	transition frequency	$I_C = 50 \text{ mA}; V_{CE} = 10 \text{ V}; f = 100 \text{ MHz}$	100	–	MHz

Switching times (between 10% and 90% levels)

t_{on}	turn-on time	$I_{Con} = 100 \text{ mA}; I_{Bon} = 5 \text{ mA};$	–	250	ns
t_{off}	turn-off time	$I_{Boff} = -5 \text{ mA}$	–	1	μs

Note

1. Pulse test: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.01$.

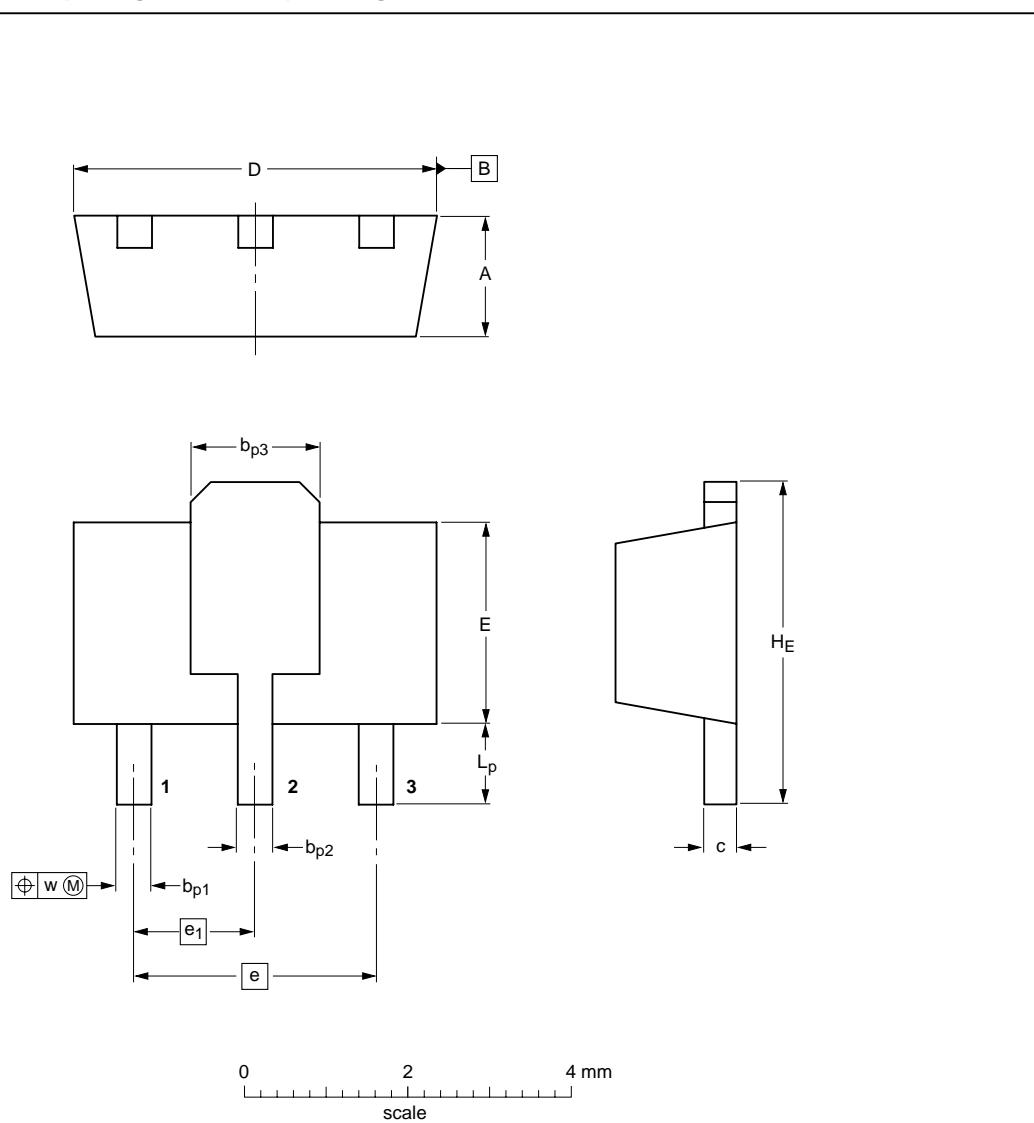
NPN medium power transistors

BSR40; BSR41; BSR42;
BSR43

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

UNIT	A	b _{p1}	b _{p2}	b _{p3}	c	D	E	e	e ₁	H _E	L _p	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT89		TO-243	SC-62			-04-08-03- 06-03-16